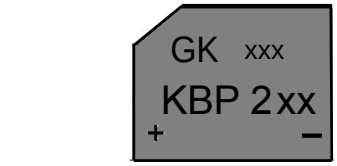
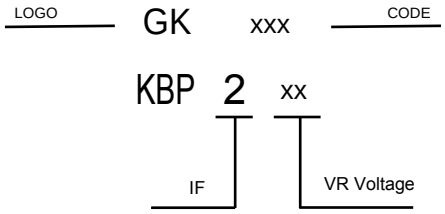
FEATURES

* Ideal for printed circuit board
* Low forward voltage
* Low leakage current
* Polarity: marked on body
* Mounting position: Any

VOLTAGE RANGE
600 to 1000 Volts
CURRENT
2.0 Ampere





MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25℃ ambient temperature uniess otherwies specified.
Single phase half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

TYPE NUMBER	Symbols	KBP206	KBP208	KBP210	Units
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	600	800	1000	Volts
Maximum RMS Voltage	V_{RMS}	420	560	700	Volts
Maximum DC Blocking Voltage	V_{DC}	600	800	1000	Volts
Maximum Average Forward Rectified Current	$I_{(AV)}$	2.0			Amp
Peak Forward Surge Current, 8.3ms single half-sine-wave superimposed on rated load (JEDEC method)	I_{FSM}	50			Amp
Maximum Forward Voltage at 2.0A DC and 25℃	V_F	1.1			Volts
Maximum Reverse Current at T_A=25℃	I_R	10.0			uAmp
at Rated DC Blocking Voltage T_A=100℃		500			
Typical Junction Capacitance (Note 1)	C_J	25			pF
Typical Thermal Resistance (Note 2)	$R_{\theta JA}$	30			℃/W
Typical Thermal Resistance (Note 2)	$R_{\theta JL}$	16			℃/W
Operating and Storage Temperature Range	T_J, Tstg	-55 to +150			℃

NOTES:

1- Measured at 1 MH_Z and applied reverse voltage of 4.0 VDC.

2- Thermal Resistance Junction to Ambient and form junction to lead at 0.375"(9.5mm) lead length P.C.B. Mounted.

RATING AND CHARACTERISTIC CURVES

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

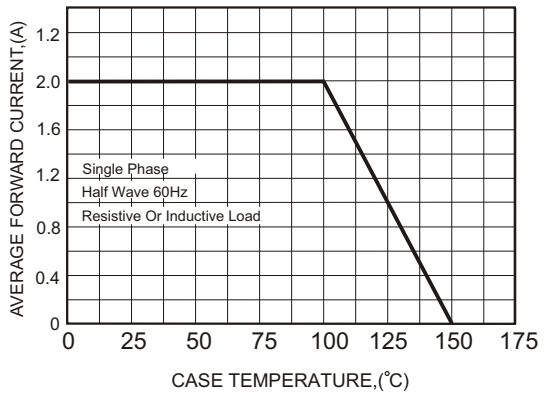


FIG.2-TYPICAL FORWARD CHARACTERISTICS

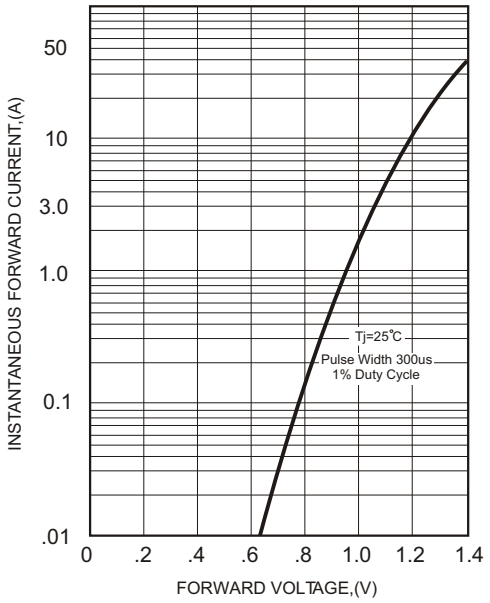


FIG.3 - TYPICAL REVERSE CHARACTERISTICS

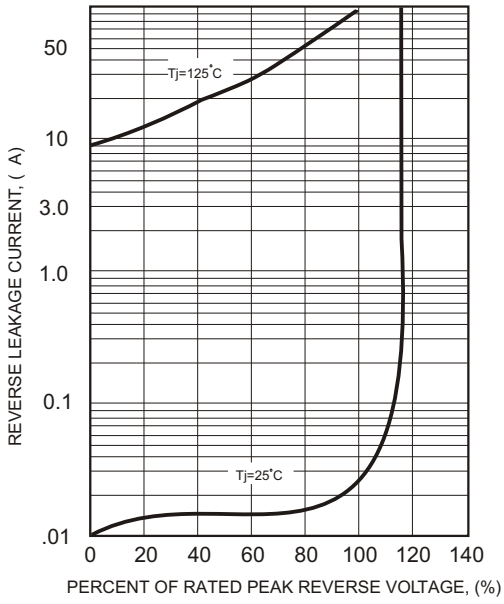
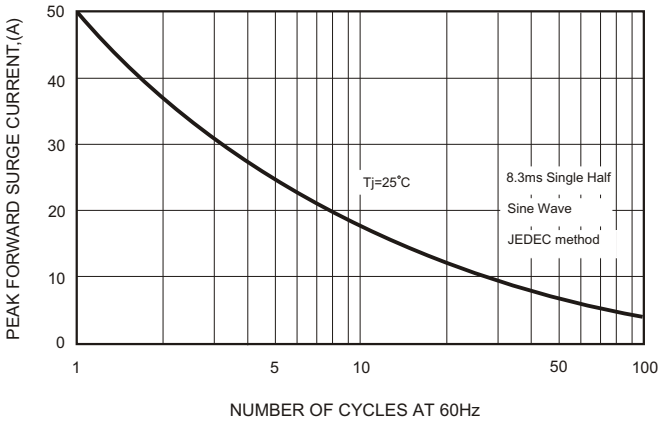


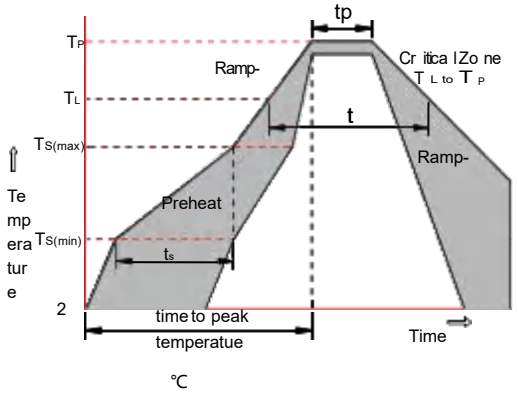
FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT



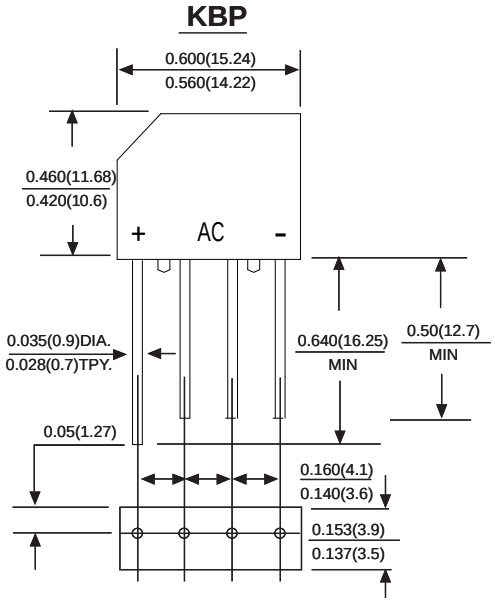
Soldering parameters

Reflow Condition		Pb-Free assembly (see as bellow)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150℃
	-Temperature Max($T_{s(max)}$)	+200℃
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3℃/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3℃/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217℃
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)℃
Time within 5℃ of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6℃/sec. Max
Time 25℃ to Peak Temp (T_P)		8 min. Max
Do not exceed		+260℃

FIG5: Reflow condition



Package Dimensions & Suggested Pad Layout



Dimensions in inches and (millimeters)